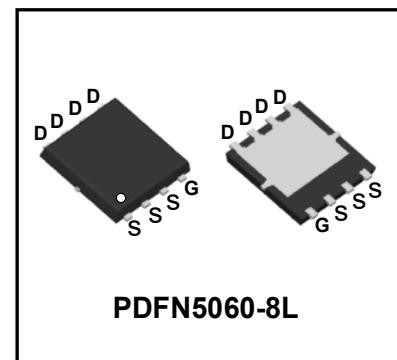


# WMB90P03TS

## 30V P-Channel Enhancement Mode Power MOSFET

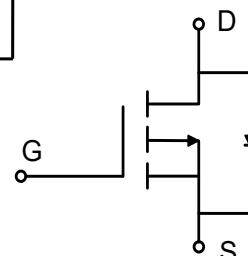
### Description

WMB90P03TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.



### Features

- $V_{DS} = -30V$ ,  $I_D = -90A$   
 $R_{DS(on)} < 4.5m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(on)} < 6.2m\Omega$  @  $V_{GS} = -4.5V$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



### Applications

- Power Management Switches
- DC/DC Converter

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_C=25^\circ C$	$I_D$	-90	A
$T_C=100^\circ C$		-57	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-360	A
Single Pulse Avalanche Energy <sup>2</sup>	$EAS$	125	mJ
Total Power Dissipation	$P_D$	60	W
Operating Junction and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	55	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	2.08	°C/W

# WMB90P03TS

## Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$	$I_{DSS}$	$V_{DS} = -30V, V_{GS} = 0V$	-	-	-1	$\mu\text{A}$
			-	-	-100	
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	$R_{DS(\text{on})}$	$V_{GS} = -10V, I_D = -30\text{A}$	-	3.5	4.5	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -15\text{A}$	-	4.8	6.2	
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS} = -10V, I_D = -30\text{A}$	-	90	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V,$ $f = 1\text{MHz}$	-	5070	-	$\text{pF}$
Output Capacitance	$C_{oss}$		-	695	-	
Reverse Transfer Capacitance	$C_{rss}$		-	580	-	
Gate resistance	$R_g$	$f = 1\text{MHz}$	-	4	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = -10V, V_{DS} = -15V,$ $I_D = -30\text{A}$	-	146	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	21.5	-	
Gate-Drain Charge	$Q_{gd}$		-	39	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -15V,$ $R_G = 3\Omega, I_D = -30\text{A}$	-	23	-	$\text{ns}$
Rise Time	$t_r$		-	15	-	
Turn-Off Delay Time	$t_{d(off)}$		-	129	-	
Fall Time	$t_f$		-	28	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = -30\text{A}, V_{GS} = 0V$	-	-	-1.2	V
Continuous Source Current $T_C=25^\circ\text{C}$	$I_S$	-	-	-	-90	A

Note :

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$
2. The EAS data shows Max. rating . The test condition is  $V_{DD} = -25V, V_{GS} = -10V, L = 0.1\text{mH}, I_{AS} = -50\text{A}$
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test..

## Typical Characteristics

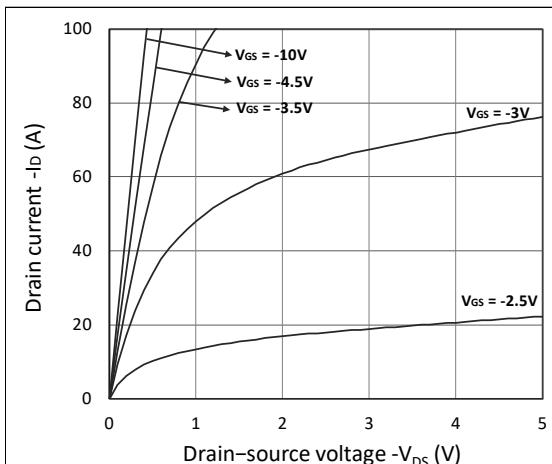


Figure 1. Output Characteristics

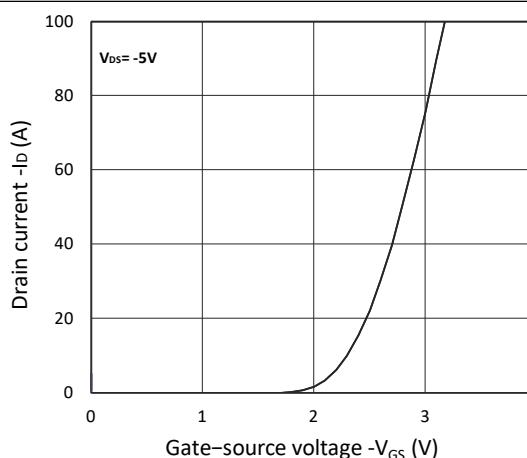


Figure 2. Transfer Characteristics

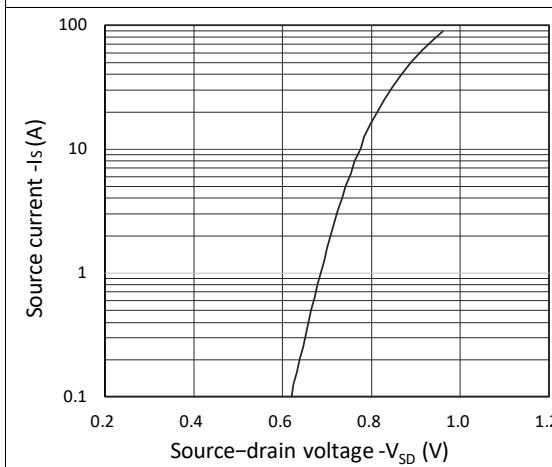
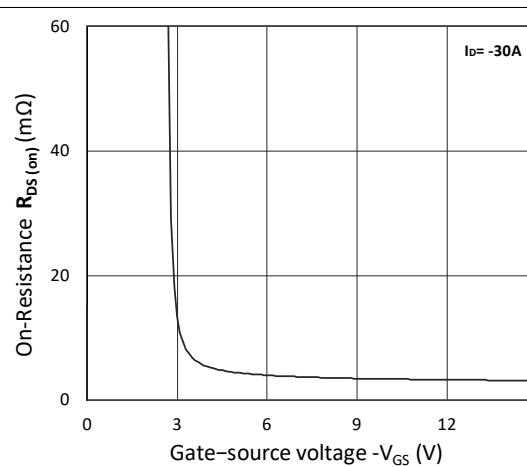
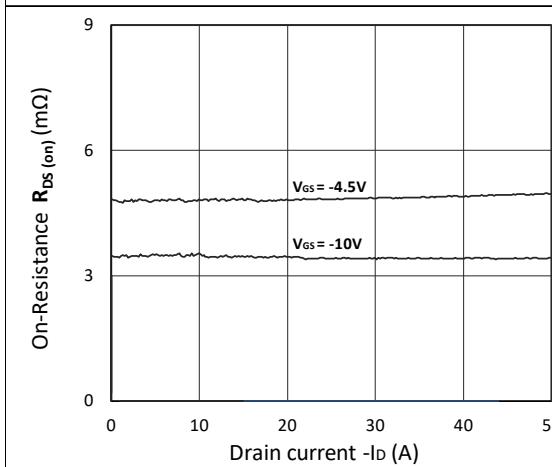
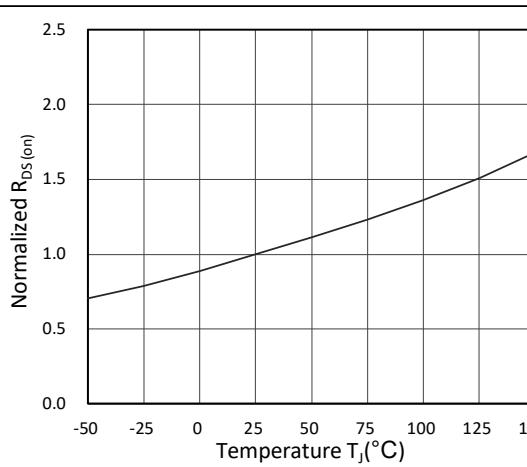
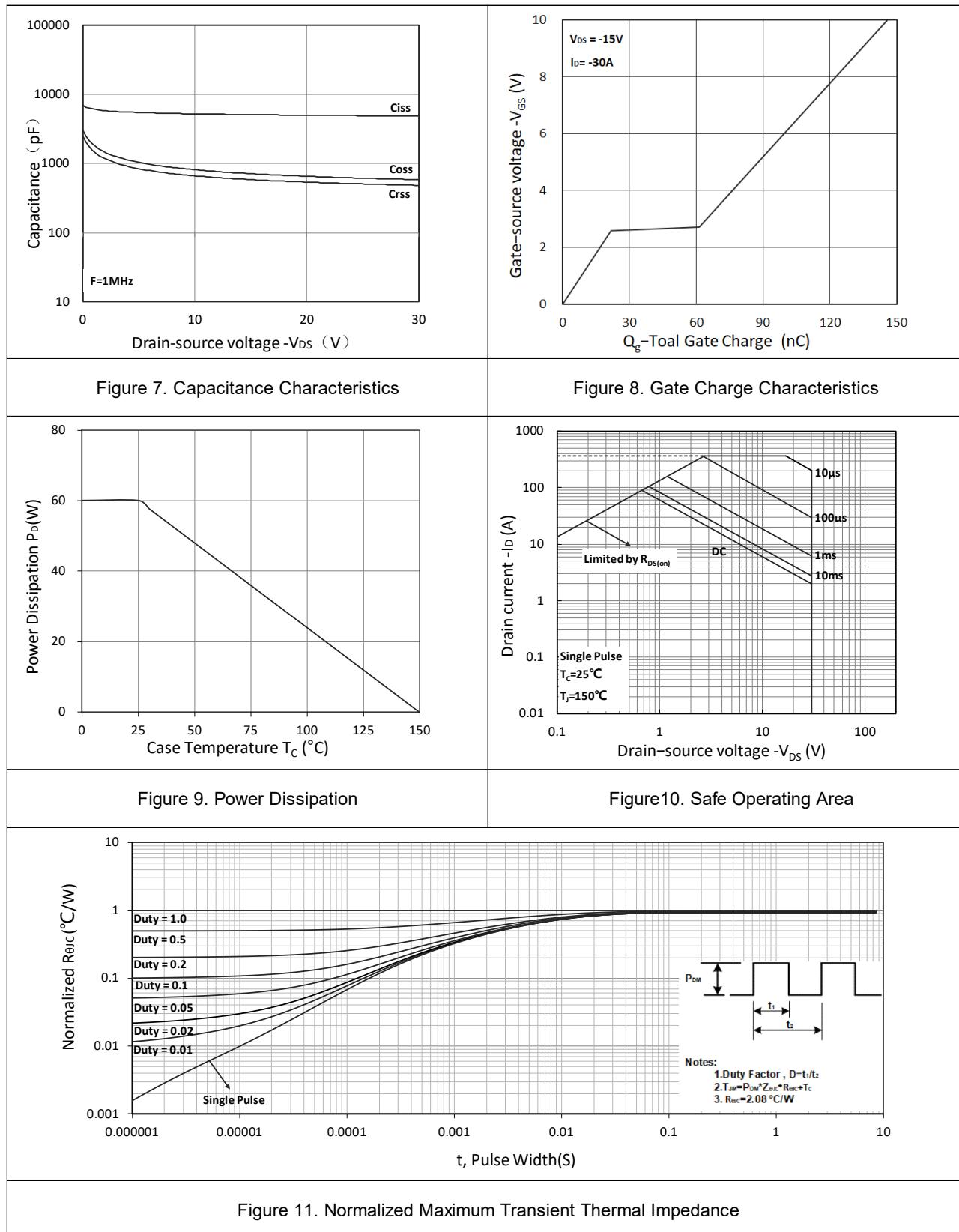
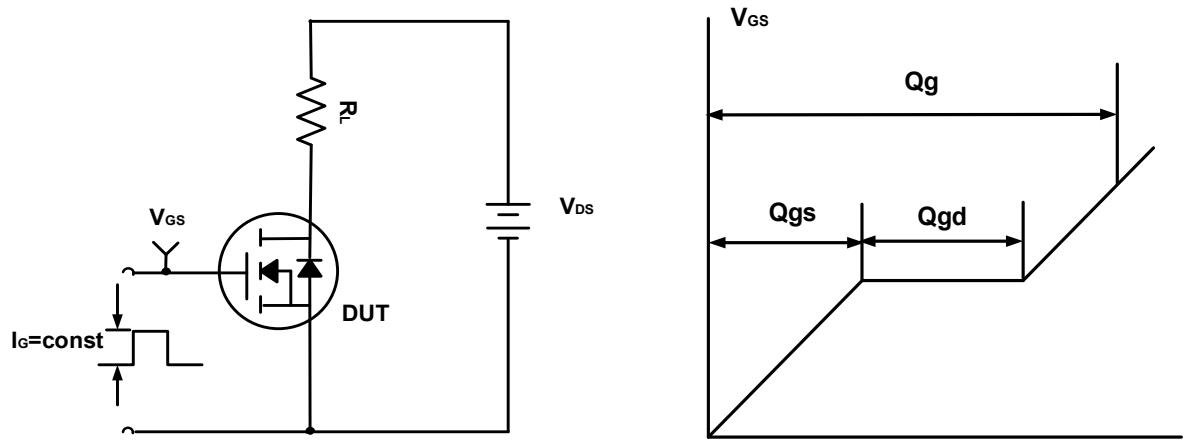
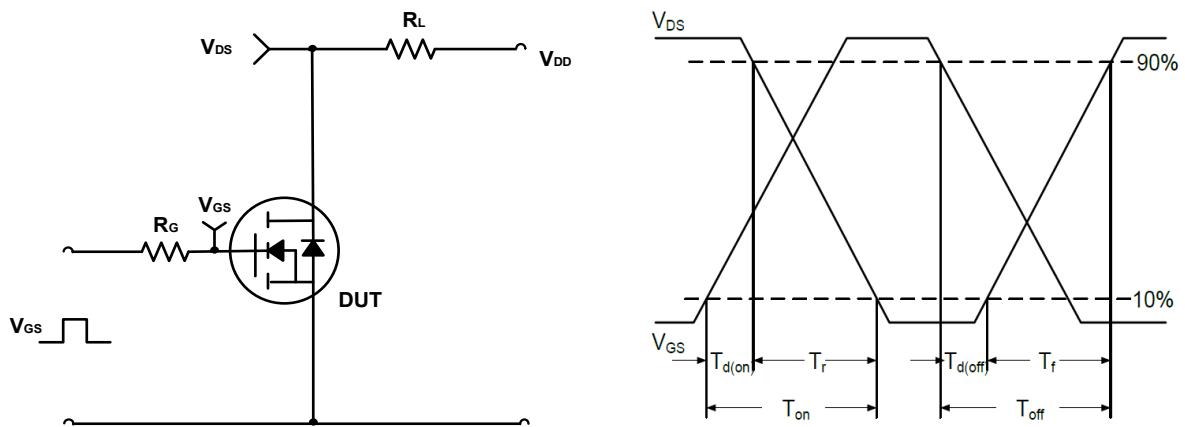
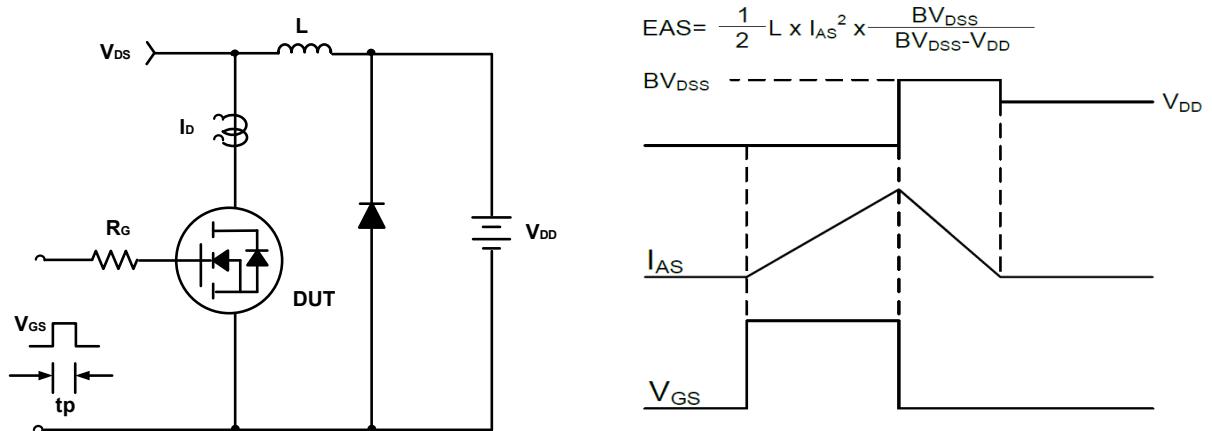


Figure 3. Forward Characteristics of Reverse

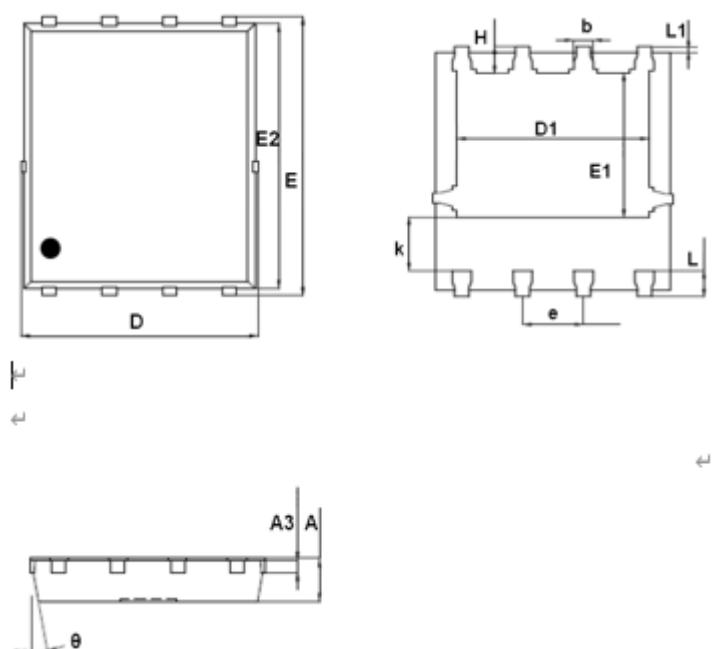
Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature



**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for PDFN5060-8L

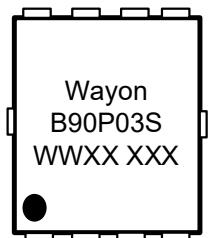
## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.71
θ	0°	12°

**Ordering Information**

Part	Package	Marking	Packing method
WMB90P03TS	PDFN5060-8L	B90P03S	Tape and Reel

**Marking Information**

B90P03S = Device code

WWXX XXX= Date code